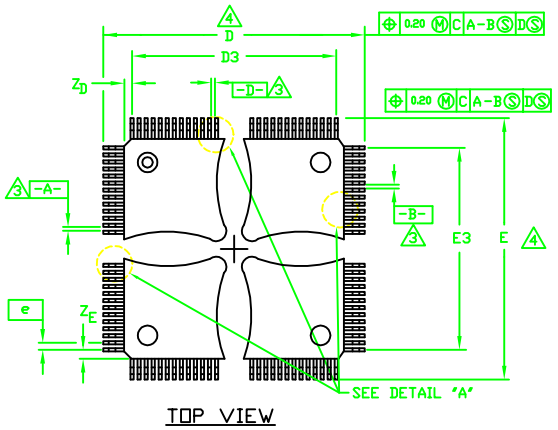
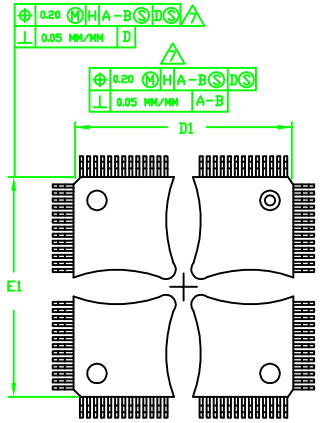
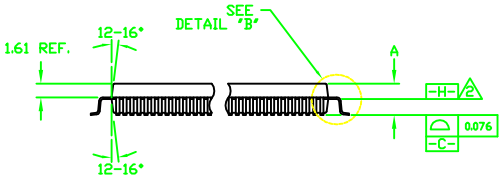


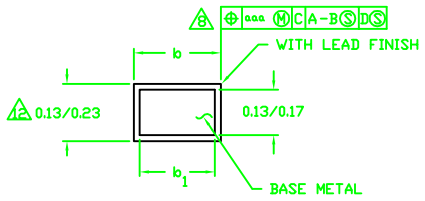
TOP VIEW



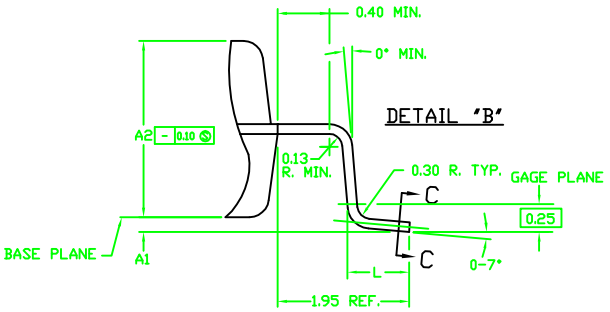
BOTTOM VIEW

REV.	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE PER DCN #A33456.	02/02 1991	H.J.C.
01	INC. PER DCN #A33573.	04/19 1991	H.J.C.
02	INC. PER DCN #A33841.	06/29 1991	H.J.C.
03	INC. PER DCN #A34701.	02/27 1992	Y.M.K.
04	INC. PER DCN #A35395.	08/18 1992	Y.M.K.
05	REVISED PER DCN #D21893. (ENG-AF-315 BECOMES 32021/05)	12/28 1994	Y.M.K.
06	REVISED PER DCN #D22210.	02/15 1995	Y.M.K.
07	REVISED PER DCN #A44831.	09/15 1999	SO KANG

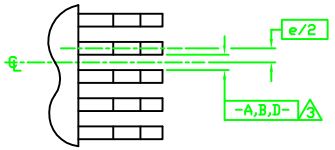




SECTION C-C



DETAIL "B"



DETAIL "A"

DECIMAL ANGULAR
XX± °±
XXX±
XXXX±

MATERIAL

FINISH

DO NOT SCALE DRAWING

PROJECTION

APPROVALS		DATE
DRAWN	T. KHAM	10/06 1994
CHECKED	K. MURRAY	10/06 1994
ENG'R	K. MURRAY	10/06 1994
RELEASED	SO KANG	09/15 1999

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Irving, Texas 75063

Excellence in semiconductor assembly

anam amkor

TITLE
PACKAGE OUTLINE, MQFP, 28 MM X 28 MM BODY, 1.95/0.33 MM FORM, 3.37 MM THICK

SIZE	DWG. NO.	REV.
B	32021	07

SCALE 3/1 SHEET 1 of 2